

A POLISHING PAD WITH A PARTIAL ADHESIVE COATING

Abstract of the Disclosure

5 A method for selectively altering a polishing pad
adhesive layer includes providing a mask having
transparent regions and opaque regions and directing
radiation toward the mask so that the radiation passes
through the transparent regions and impinges onto the
adhesive layer on the polishing pad. The area of the
adhesive layer corresponding to the transparent
10 regions of the mask is cured to be less adhesive. The
area of the adhesive layer corresponding to the opaque
regions remain adhesive.

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